ABSTRACT

INTEGRATED CIRCUIT SYSTEM WITH THROUGH SILICON VIA AND METHOD OF MANUFACTURE THEREOF

A method of manufacture of an integrated circuit system includes: providing a substrate including an active device; forming a through-silicon-via into the substrate; forming an insulation layer over the through-silicon-via to protect the through-silicon-via; forming a contact to the active device after forming the insulation layer; and removing the insulation layer.

FIG. 5